

DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on) max}	I _D T _A = 25℃
201/	18mΩ @ $V_{GS} = 4.5V$	5.2A
20V	$30\text{m}\Omega$ @ V _{GS} = 1.8V	4.0A

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- Lead, Halogen, and Antimony Free, RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance (R_{DS(on)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Power management functions
- **Battery Pack**
- Load Switch

Mechanical Data

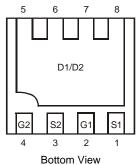
- Case: U-DFN3030-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.0172 grams (approximate)

U-DFN3030-8

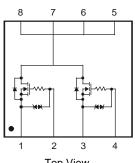


Top View

Bottom View



Bottom View Pin Configuration



Top View Equivalent Circuit

Ordering Information (Note 6)

Part Number	Case	Packaging
DMN2016LFG-7	U-DFN3030-8	3000 / Tape & Reel

Notes:

- 1. No purposefully added lead. Halogen and Antimony Free.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com. 3. For packaging details, go to our website at http://www.diodes.com

Marking Information



N20 = Product Type Marking Code YYWW = Date Code Marking YY = Last digit of year (ex: 09 for 2009) WW = Week code (01 to 53)



Maximum Ratings @T_A = 25℃ unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V_{GSS}	±8	V
Continuous Drain Current (Note 4)	Steady State	T _A = 25℃ T _A = 70℃	ID	5.2 4.1	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	30	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	P _D	0.77	W
Thermal Resistance, Junction to Ambient @T _A = 25℃ (Note 4)	R _{θJA}	169	€/W
Thermal Resistance, Junction to Case @T _A = 25℃ (Note 4)	$R_{ heta JC}$	15.8	C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	C

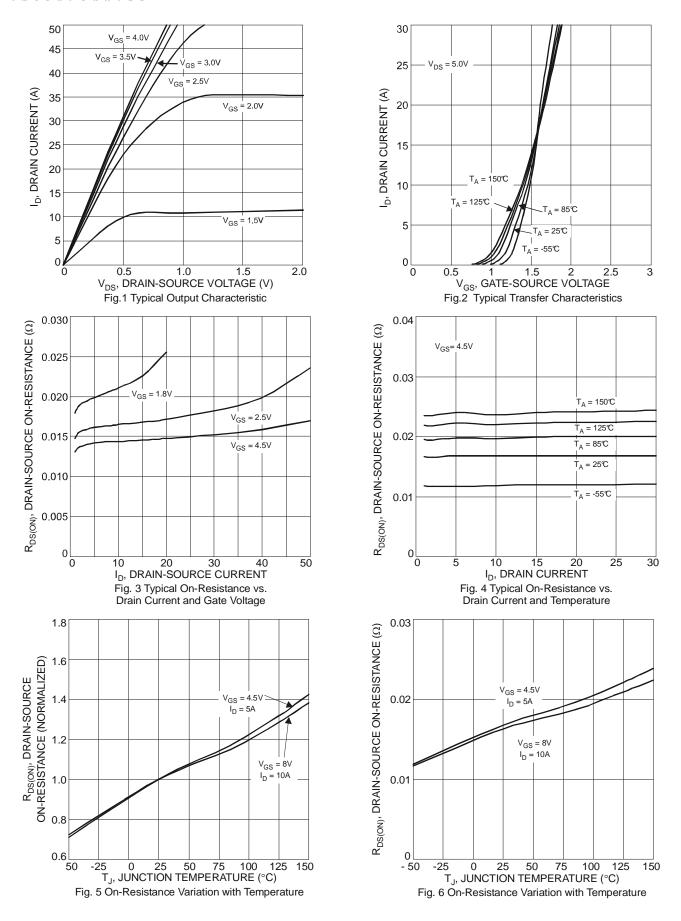
Electrical Characteristics @T_A = 25℃ unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$	
Gate-Source Breakdown Voltage	BV_GSO	±8	-	-	V	$V_{DS} = 0V, I_{G} = \pm 250 \mu A$	
Zero Gate Voltage Drain Current TJ = 25℃	IDSS	-	-	1.0	μΑ	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	-	-	±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	$V_{GS(th)}$	0.4	0.71	1.1	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
			13	18	mΩ	$V_{GS} = 4.5V, I_D = 6A$	
			13.5	19		$V_{GS} = 4.0V, I_D = 6A$	
Static Drain-Source On-Resistance	R _{DS (ON)}	-	14	20.5		$V_{GS} = 3.1V, I_D = 6A$	
			15	22		$V_{GS} = 2.5V, I_D = 6A$	
			21	30		$V_{GS} = 1.8V, I_D = 6A$	
Forward Transfer Admittance	Y _{fs}	-	25	-	S	$V_{DS} = 5V, I_{D} = 6A$	
Diode Forward Voltage	V_{SD}	-	0.75	1.0	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 6)							
Input Capacitance	C _{iss}	-	1472	-	pF	101/1/	
Output Capacitance	Coss	-	311	-	pF	$V_{DS} = 10V, V_{GS} = 0V,$ -f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	-	141	-	pF	T = 1.0IVII IZ	
Gate Resistance	R _g	-	1.46	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_{g}	-	16.0	-	nC	V 45V V 40V	
Gate-Source Charge	Q_{gs}	-	36.6	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_{D} = 6A$	
Gate-Drain Charge	Q_{gd}	-	2.1	-	nC		
Turn-On Delay Time	t _{D(on)}	-	2.6	-	ns		
Turn-On Rise Time	t _r	-	13.2	-	ns	$V_{DD} = 10V, V_{GS} = 5V,$ $R_{GEN} = 3\Omega, R_L = 1.7\Omega$	
Turn-Off Delay Time	t _{D(off)}	-	84.5	-	ns		
Turn-Off Fall Time	t _f	-	46.8	-	ns		

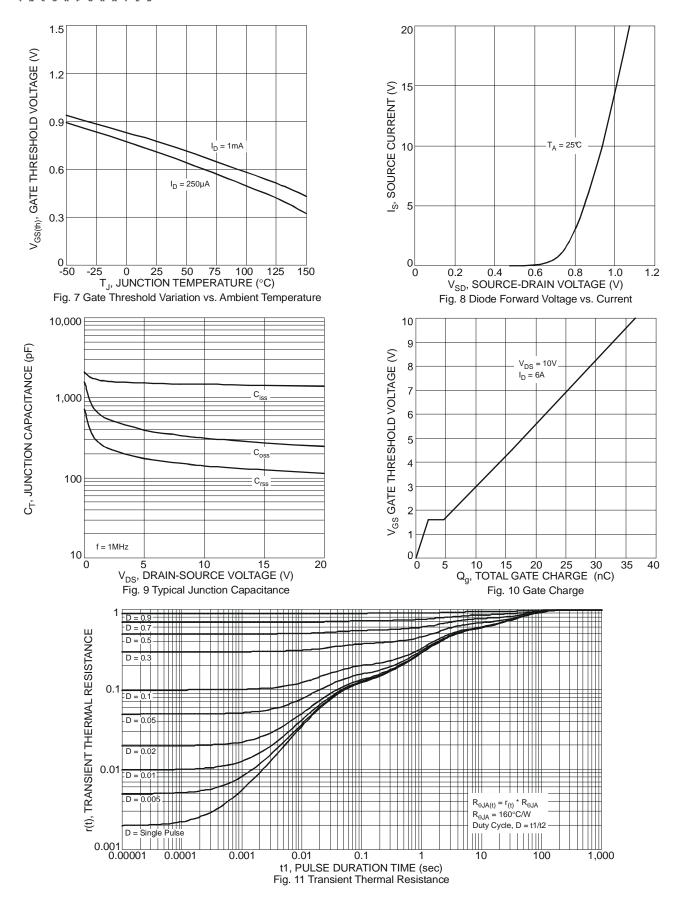
Notes:

- 4. Device mounted on FR-4 PCB, with minimum recommended pad layout.5. Repetitive rating, pulse width limited by junction temperature6. Guaranteed by design. Not subject to product testing



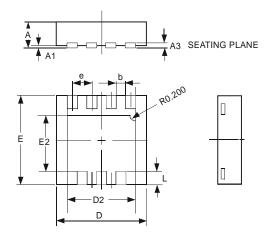






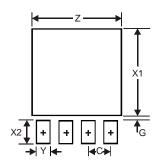


Package Outline Dimensions



U-DFN3030-8					
Dim	Min	Max	Тур		
Α	0.57	0.63	0.60		
A 1	0	0.05	0.02		
A3	—	_	0.15		
b	0.29	0.39	0.34		
D	2.90	3.10	3.00		
D2	2.19	2.39	2.29		
е	—	_	0.65		
Е	2.90	3.10	3.00		
E2	1.64	1.84	1.74		
Ĺ	0.30	0.60	0.45		
All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)		
Z	2.59		
G	0.11		
X1	2.49		
X2	0.65		
Y	0.39		
С	0.65		



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